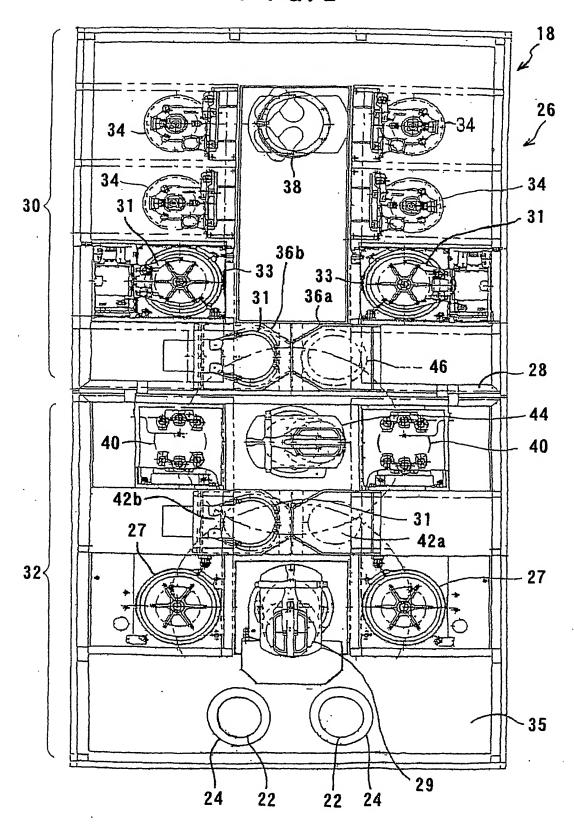
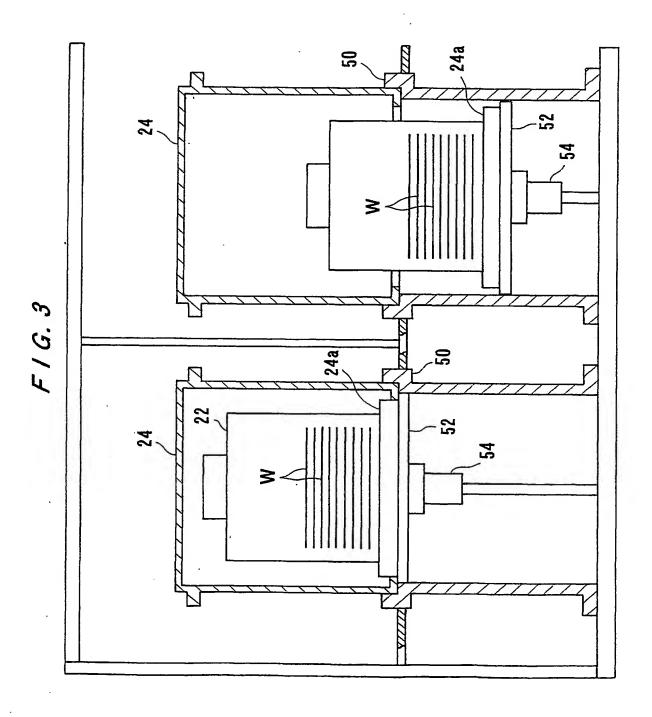


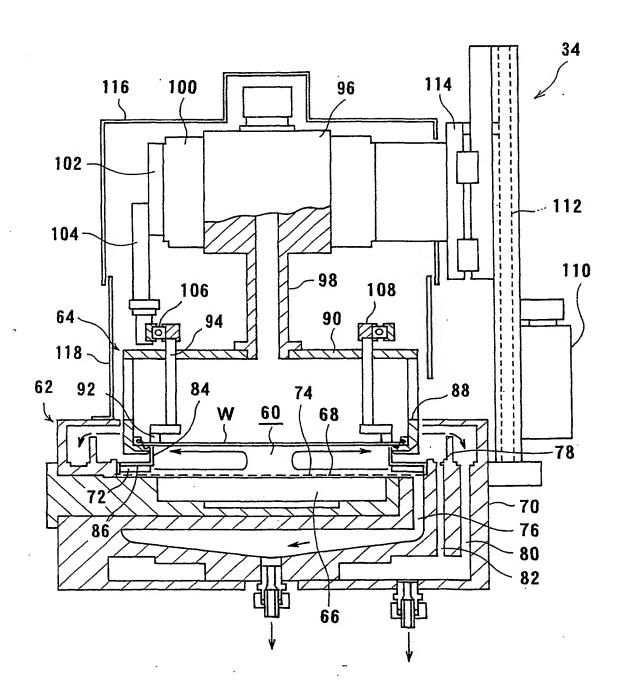
2/89 F 1 G. 2

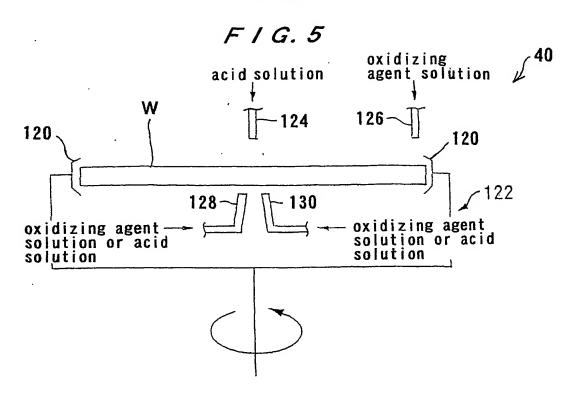


3/89

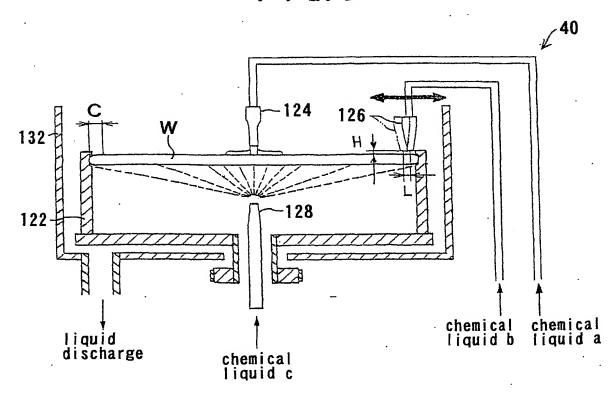


4/89 F I G. 4

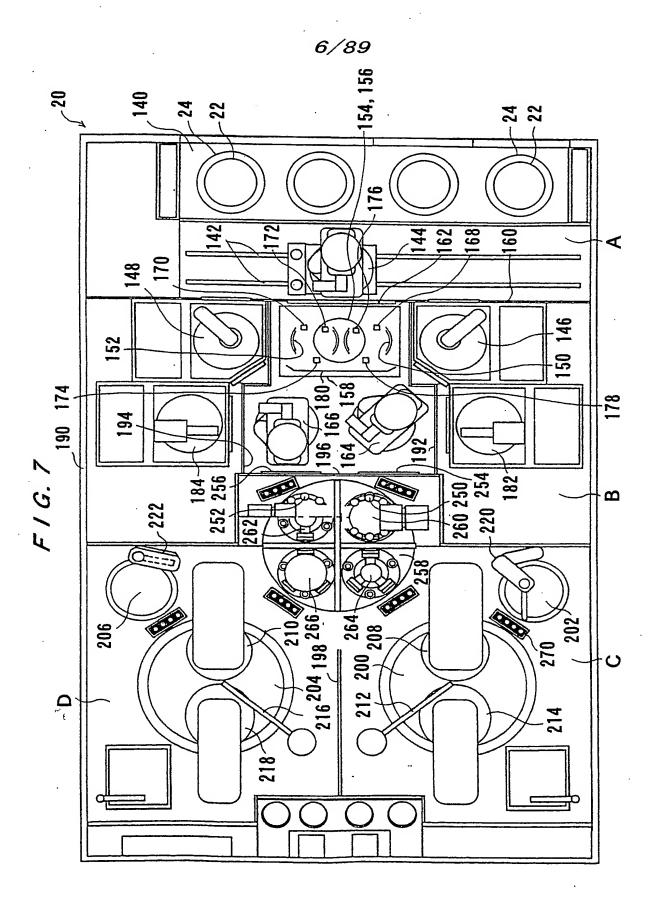


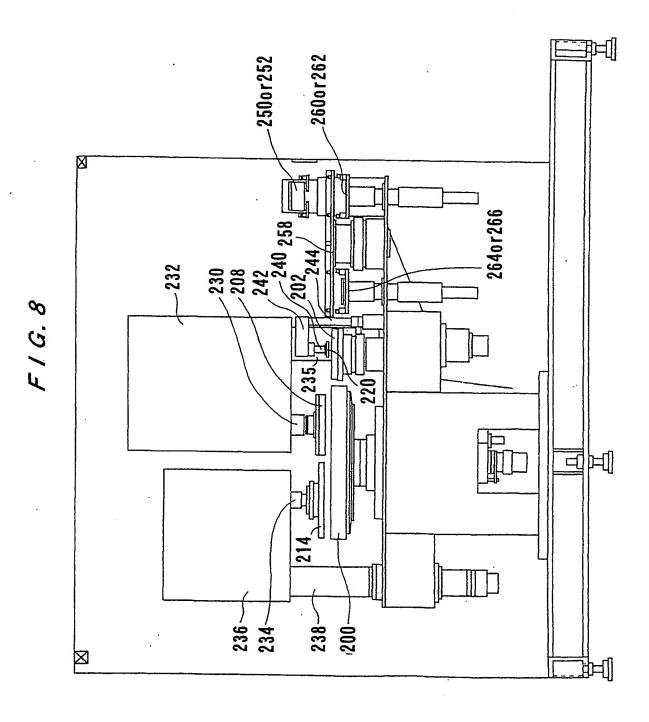


F 1 G. 6

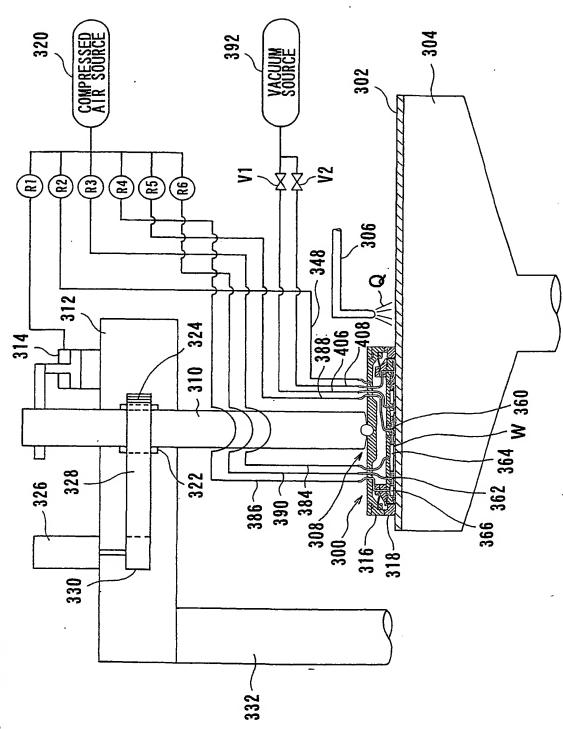


WO 02/47139 PCT/JP01/10590

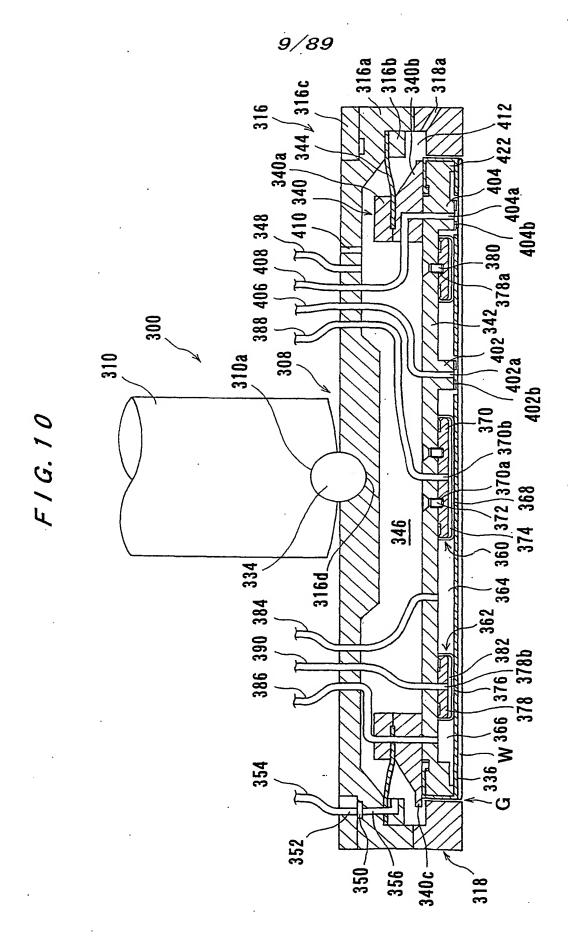




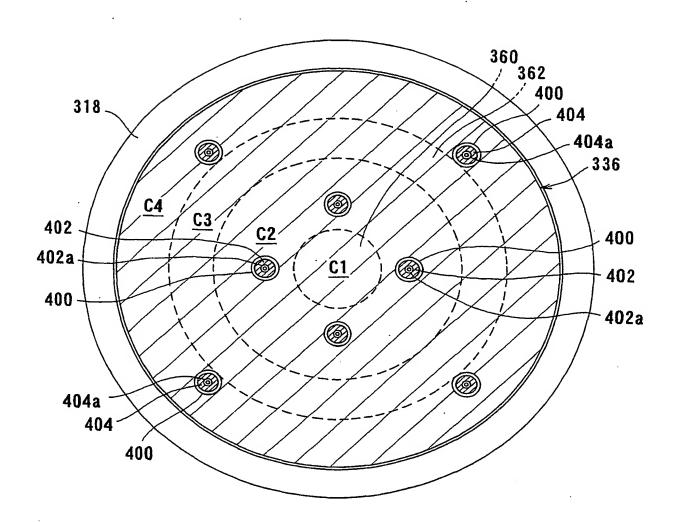
8/89



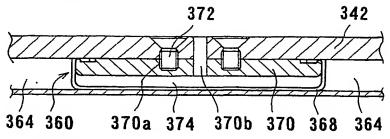
... '



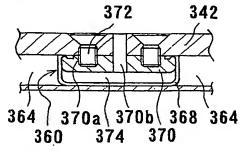
F/G.11



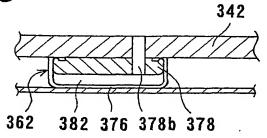




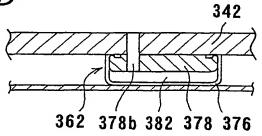
F I G. 12B



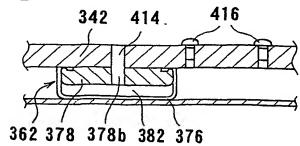
F | G. 12C



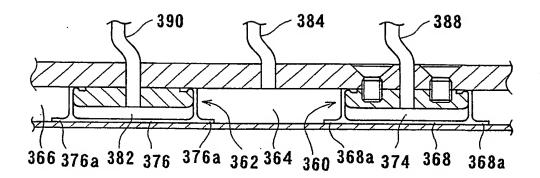
F / G. 12D



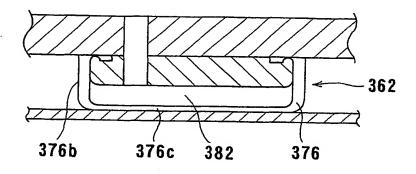
F / G. 12E



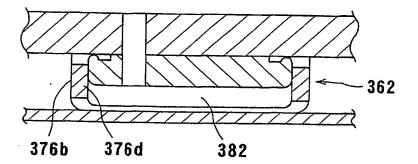
F | G. 13



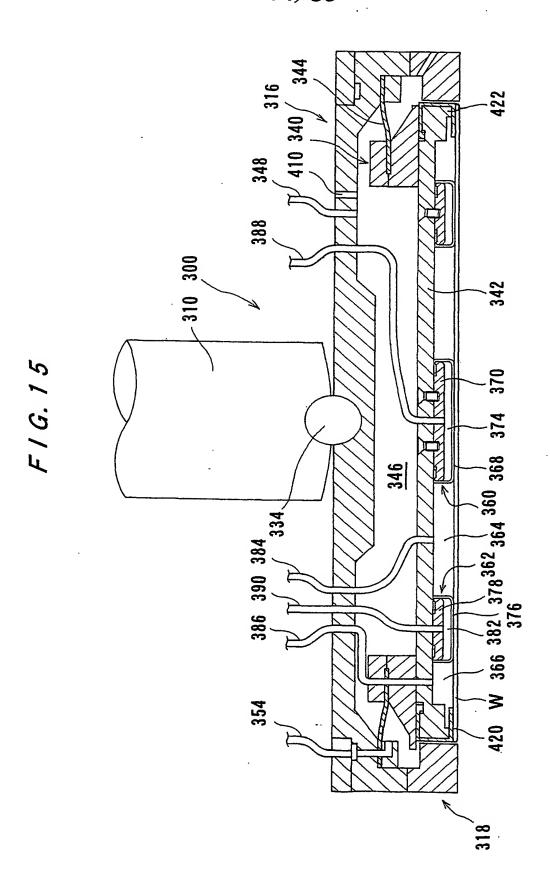
F / G. 14A



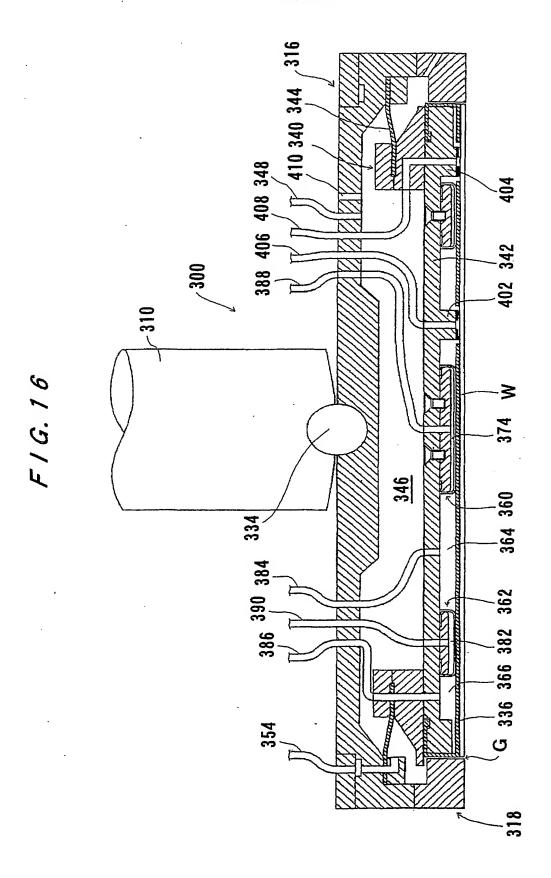
F / G. 14B



14/89

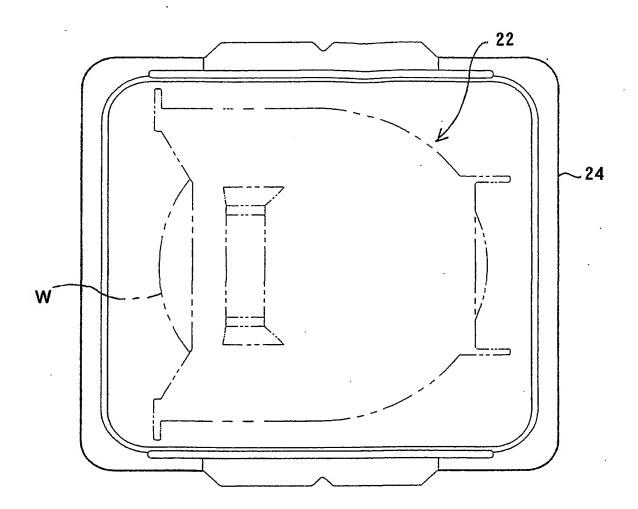


15/89

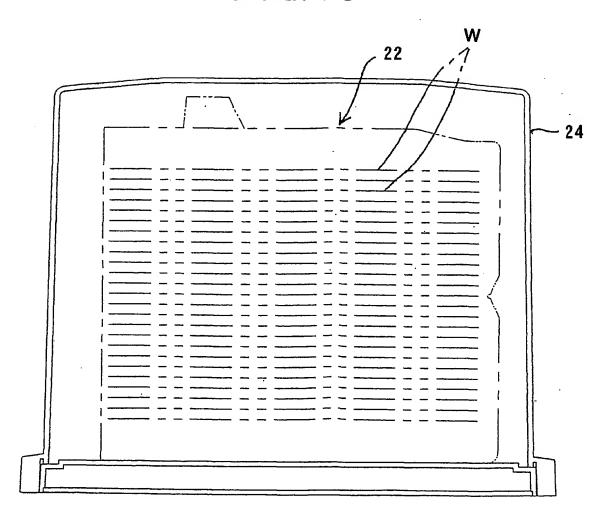


16/89.

F/G.17



F/G.18



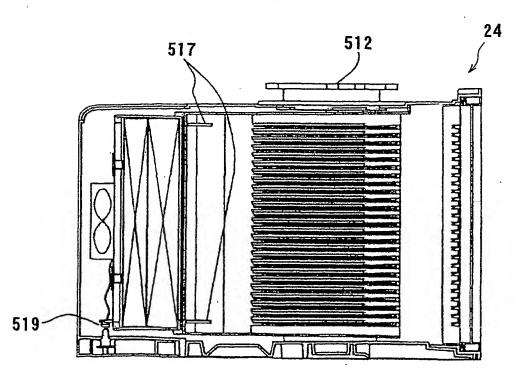


WO 02/47139 PCT/JP01/10590

18/89

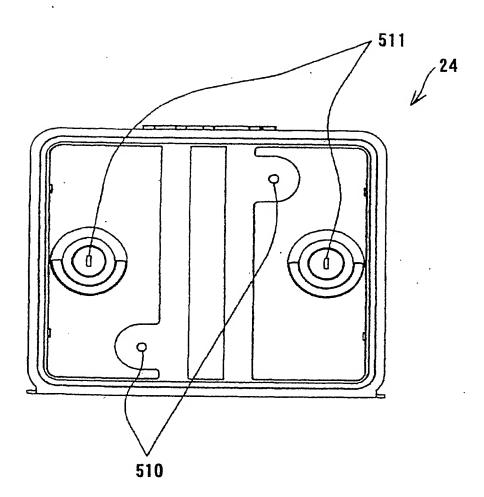
F I G. 19 24 501 513b 502 513a 503 -515 507 Α 514 516 506 505 513b 530 **5**04

F | G. 20

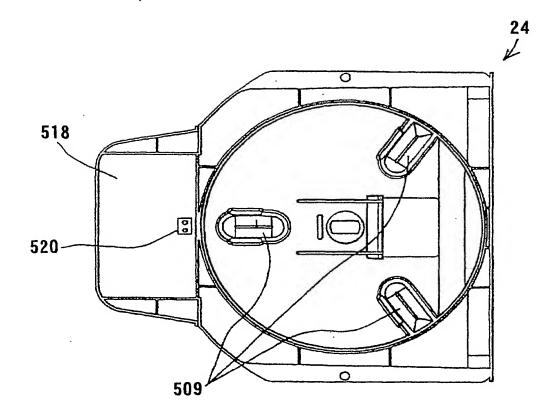




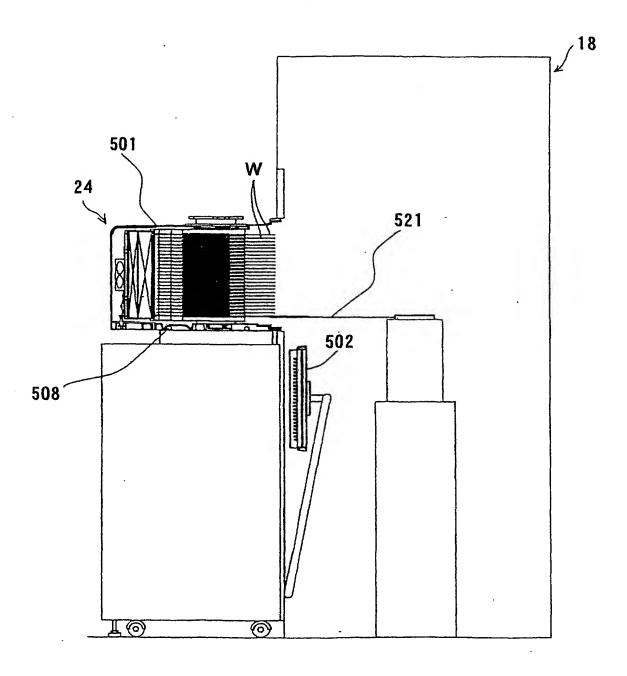
F | G. 21

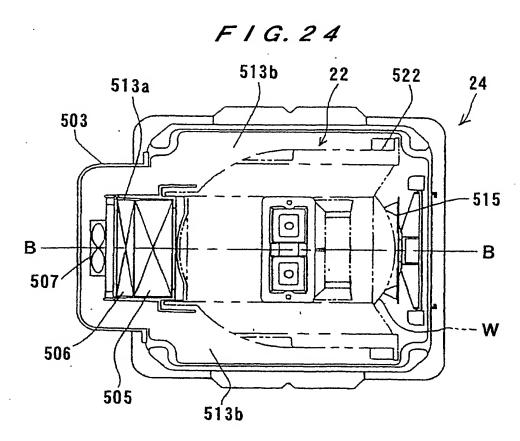


F 1 G. 22

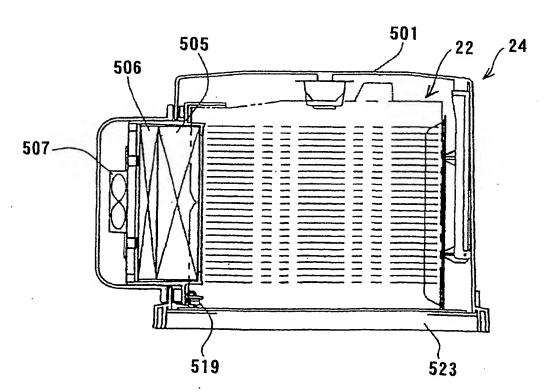


F | G. 23

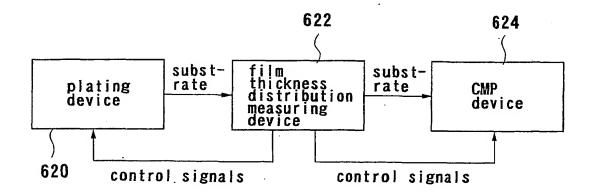




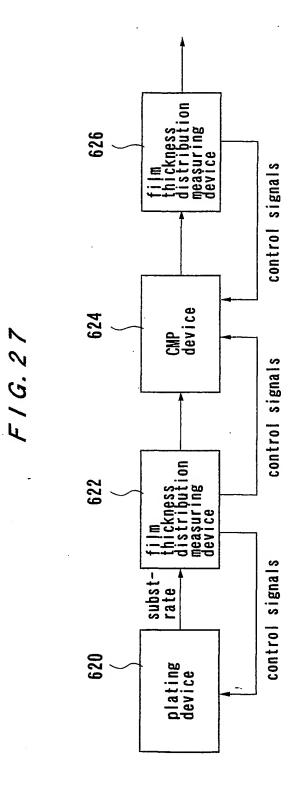
F 1 G. 25



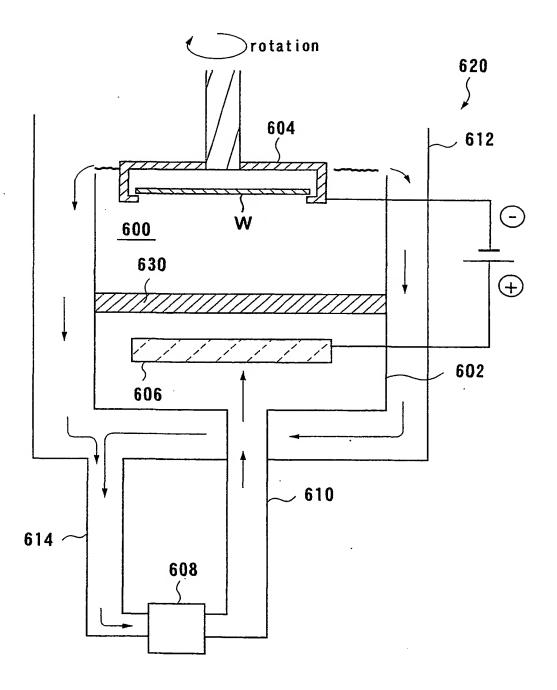
F 1 G. 26



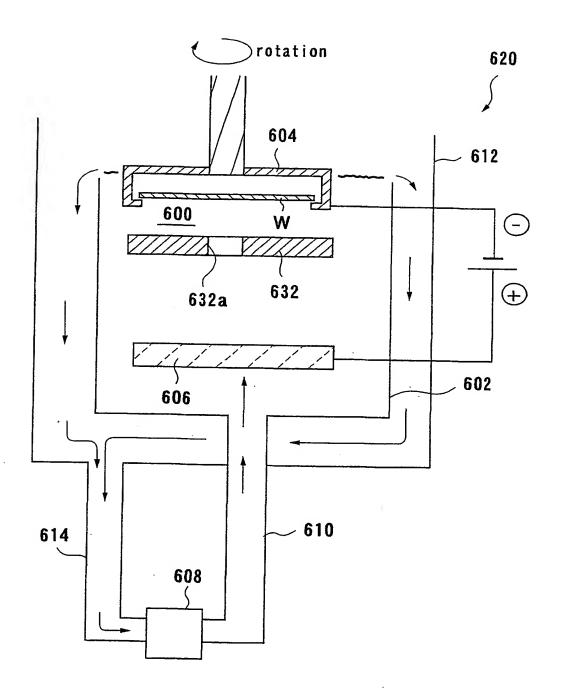
24/89



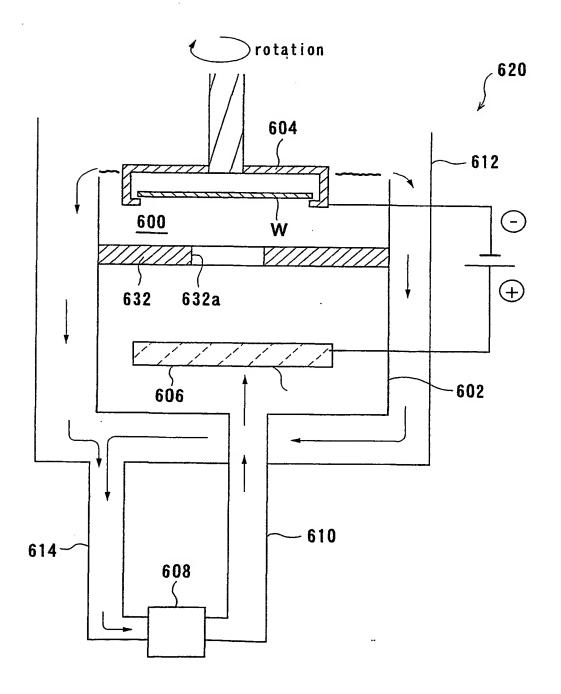
F | G. 28



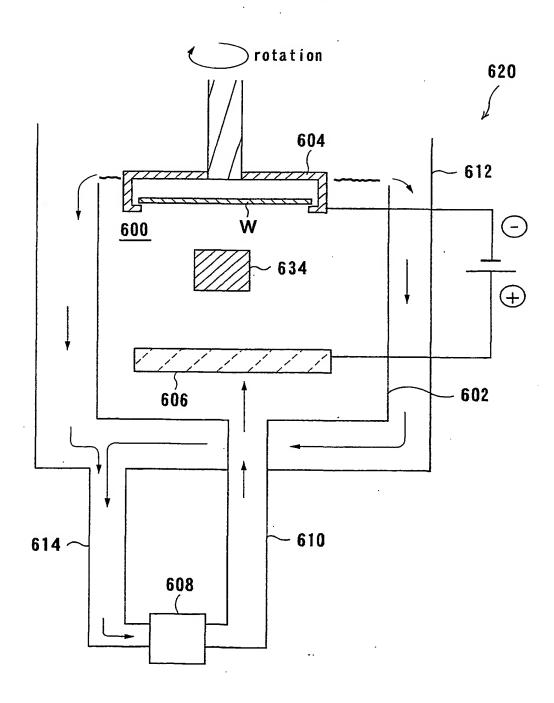
F | G. 29



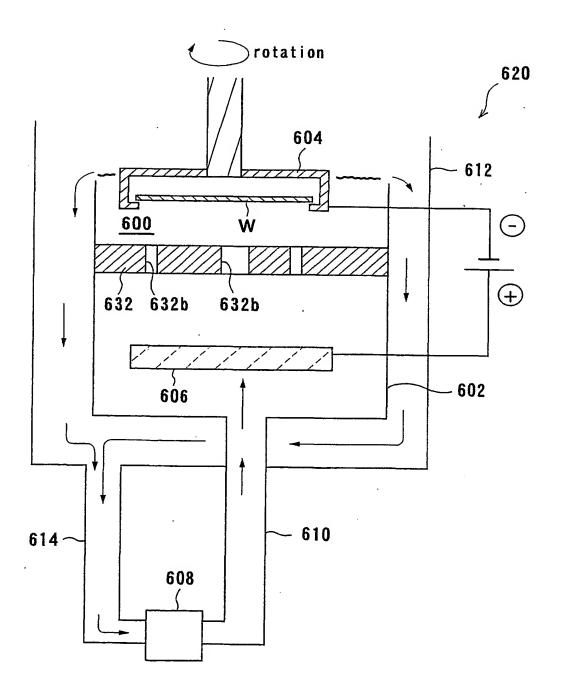
F | G. 30



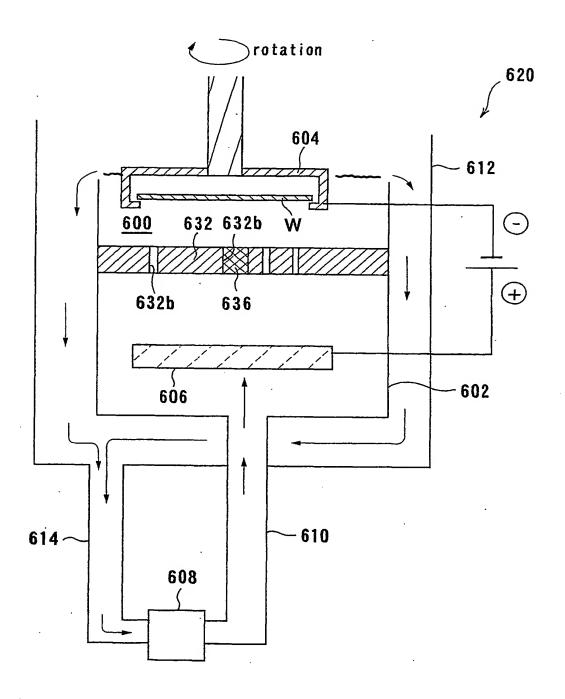
F | G. 3 1



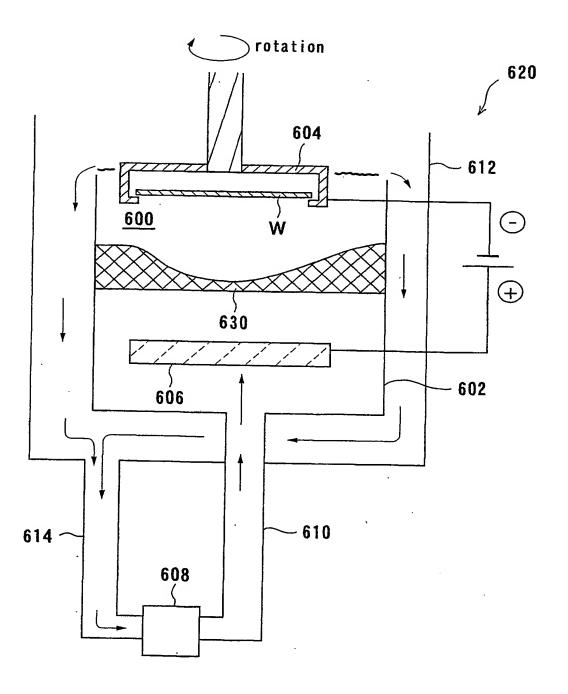
F / G. 32



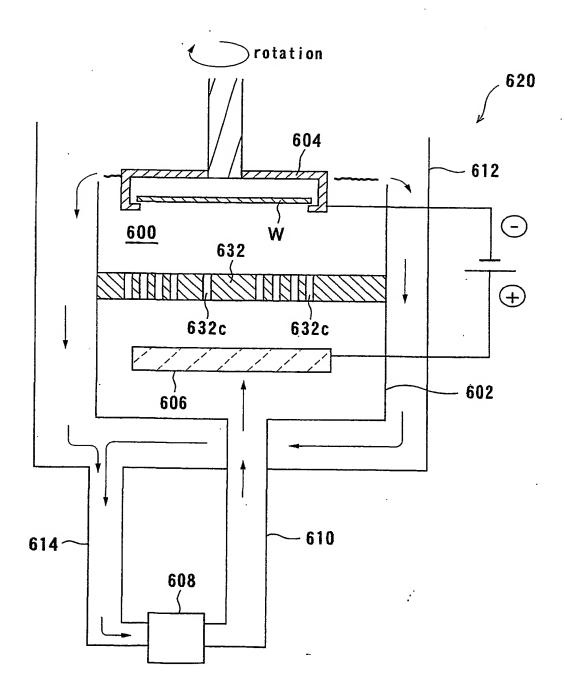
F / G. 33



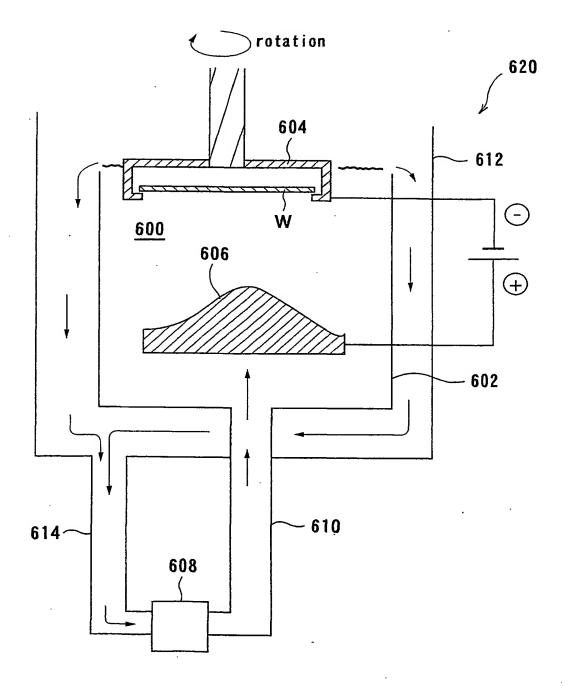
F / G. 34



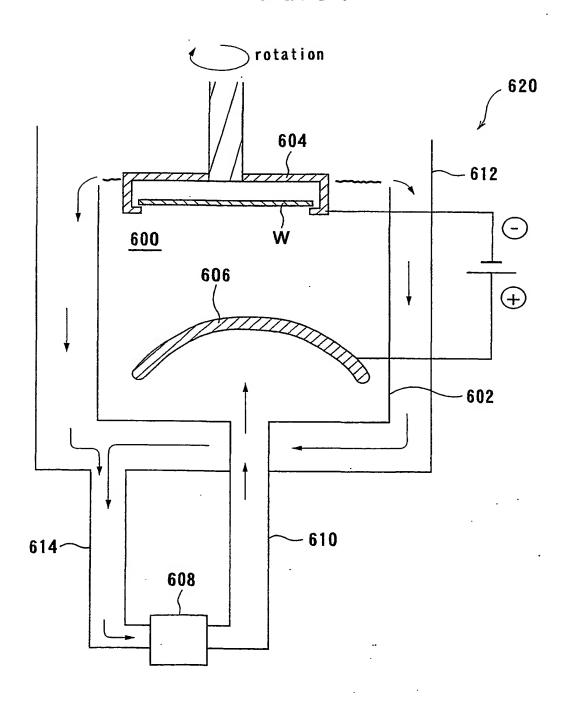
F / G. 35



F 1 G. 36

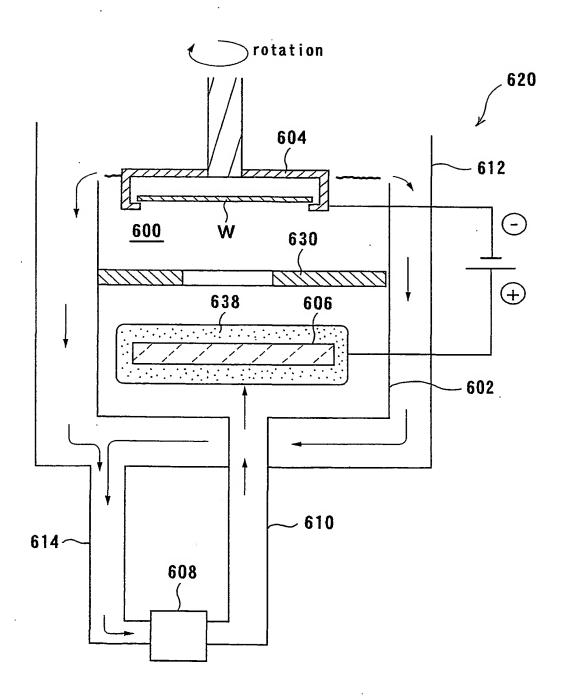


F | G. 37



35/89

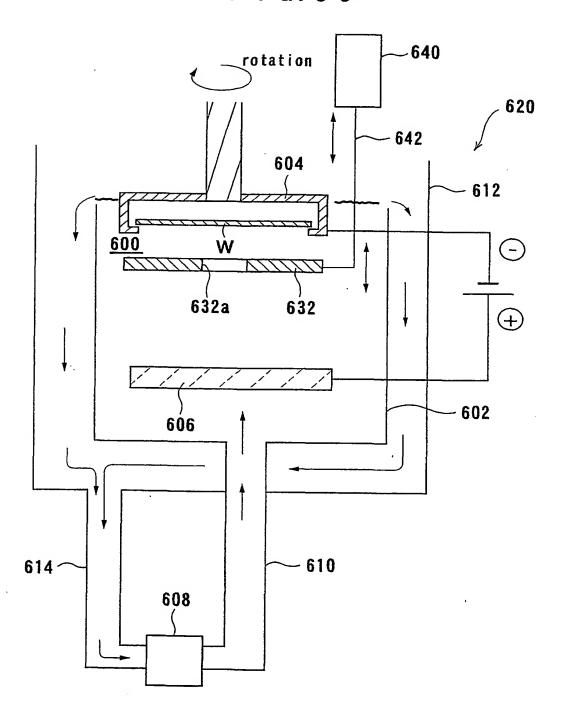
F | G. 38



WO 02/47139 PCT/JP01/10590

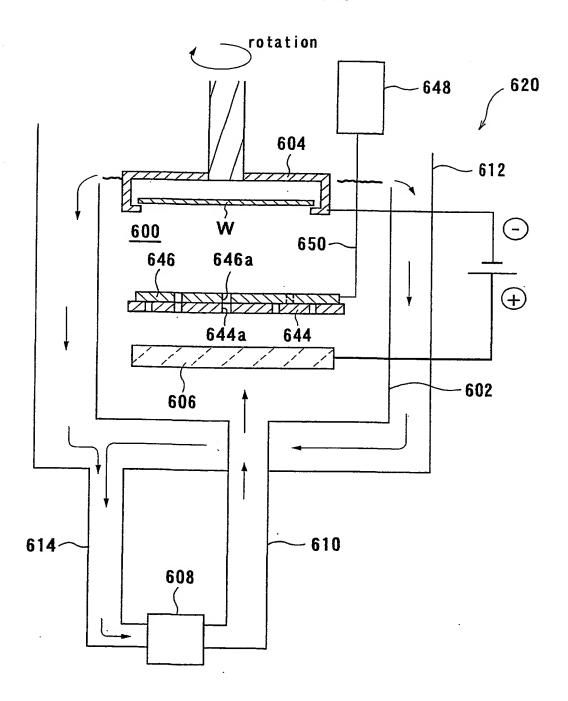
36/89

F | G. 39

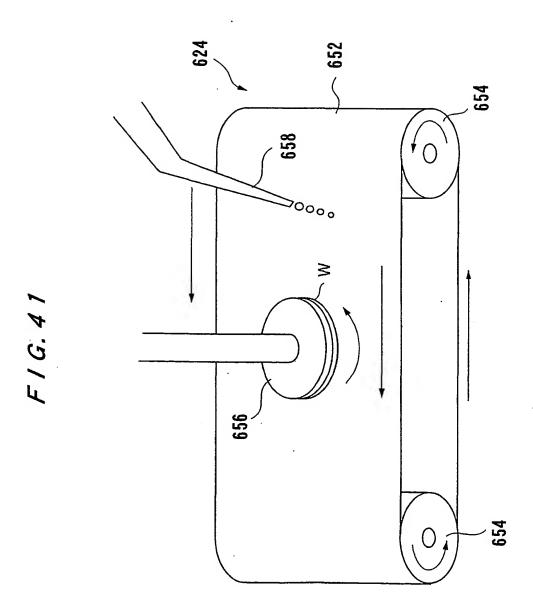


37/89

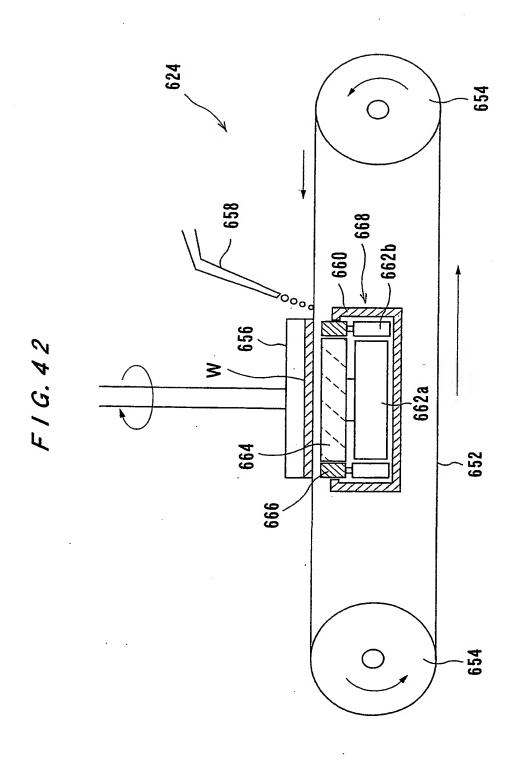
F / G. 40



38/89

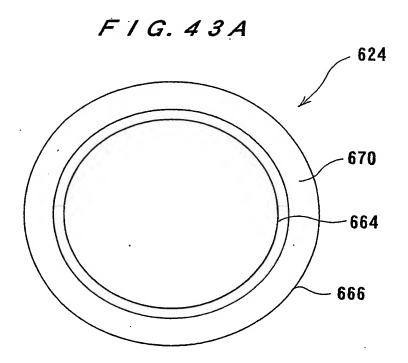


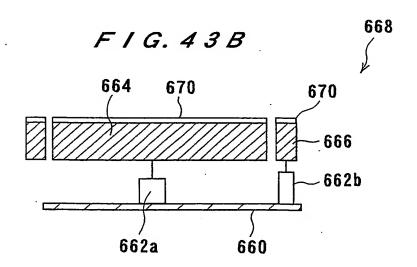
39/89



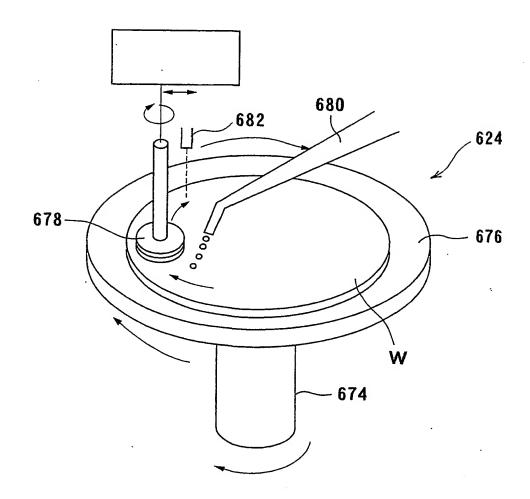
PCT/JP01/10590

40/89



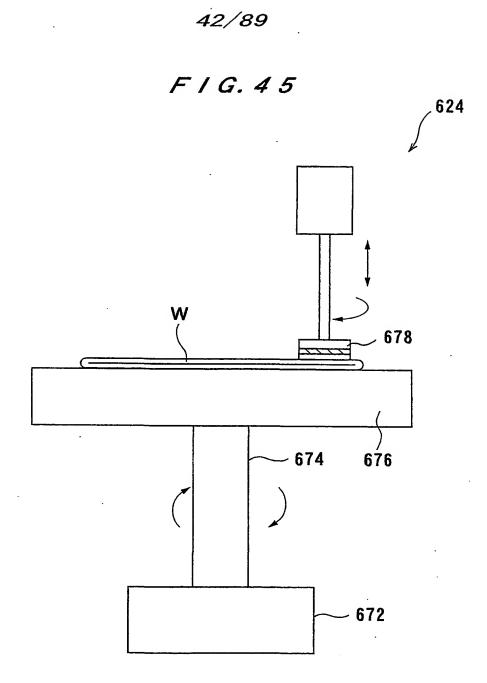


F 1 G. 44

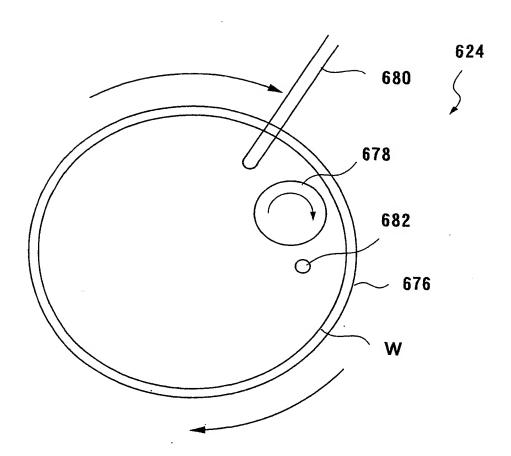


WO 02/47139 PCT/JP01/10590

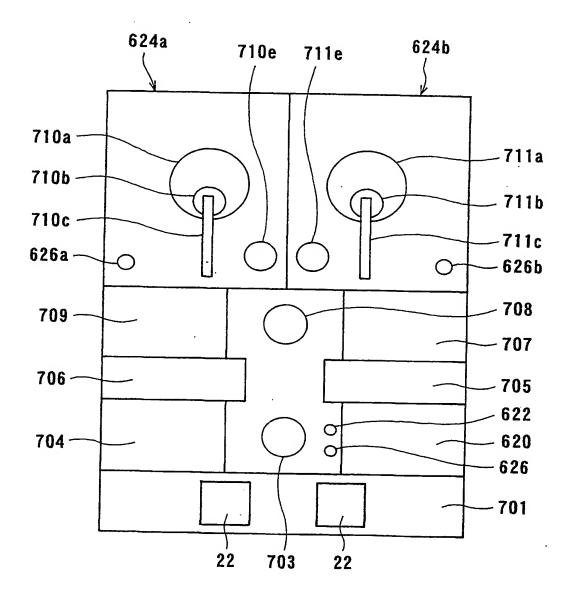




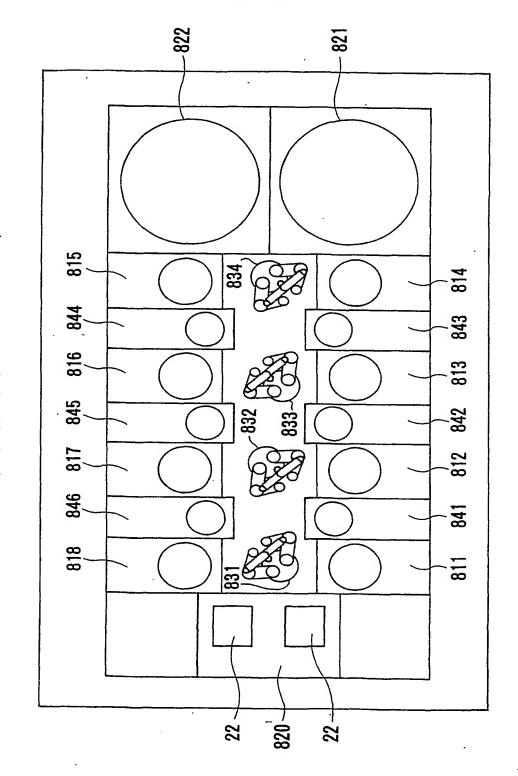
F | G. 46



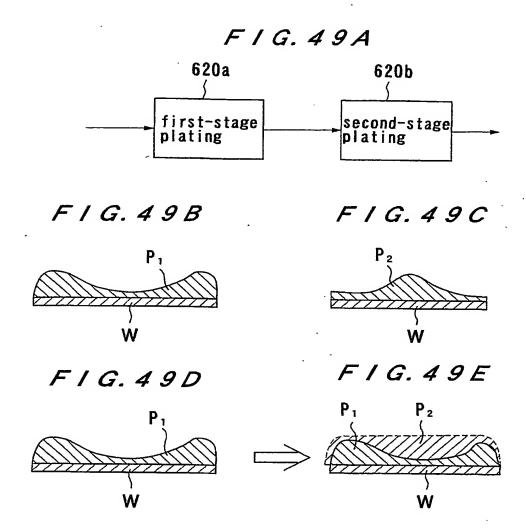
F I G. 47



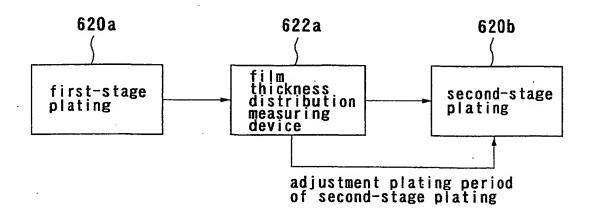
45/89



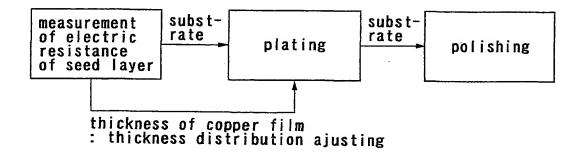
F1G.48



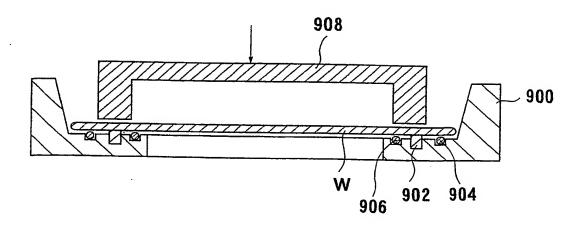
F | G. 50



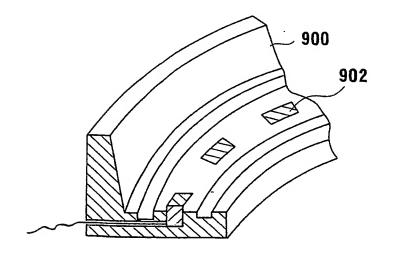
F | G. 5 1



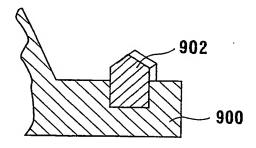
F/G.52



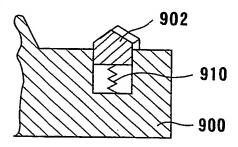
F/G.53



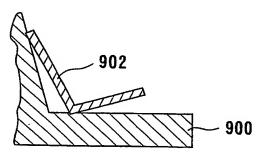
F / G. 5 4 A



F | G. 54B

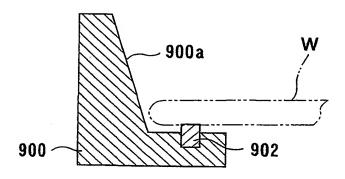


F | G. 54C

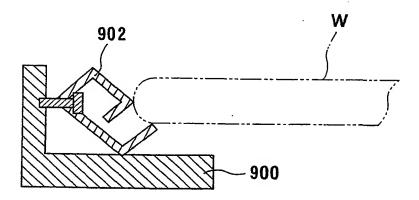


51/89

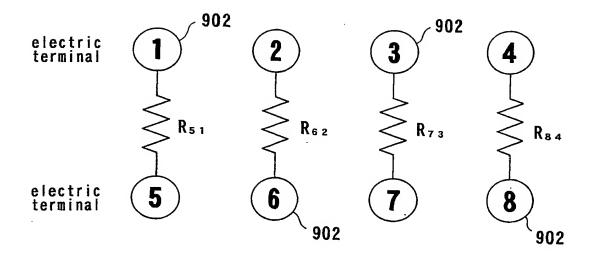
F / G. 55A



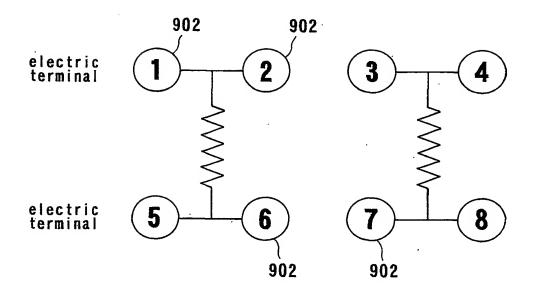
F / G. 55B



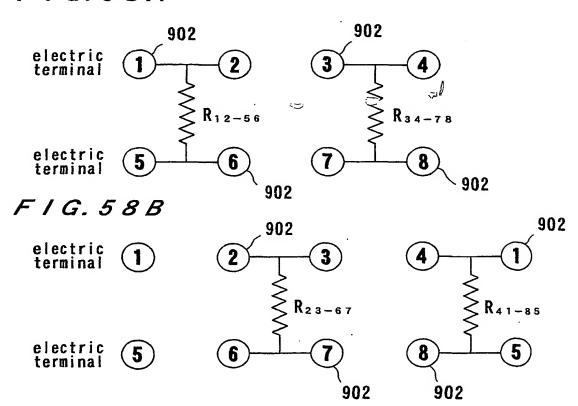
F/G.56



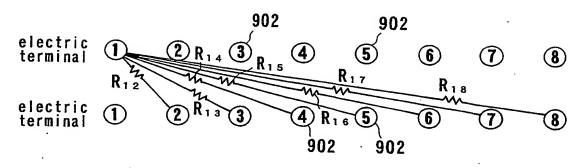
F | G. 57



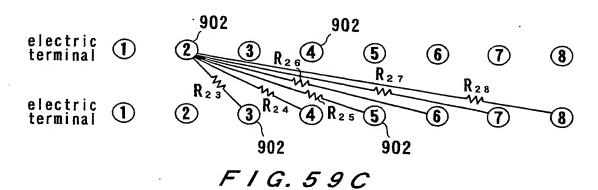
F I G. 58A

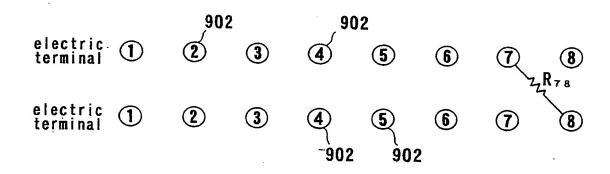


F I G. 59A

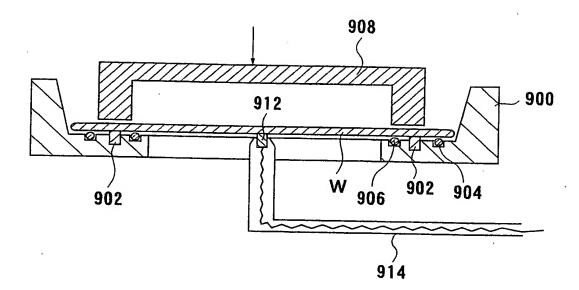


F | G. 59B

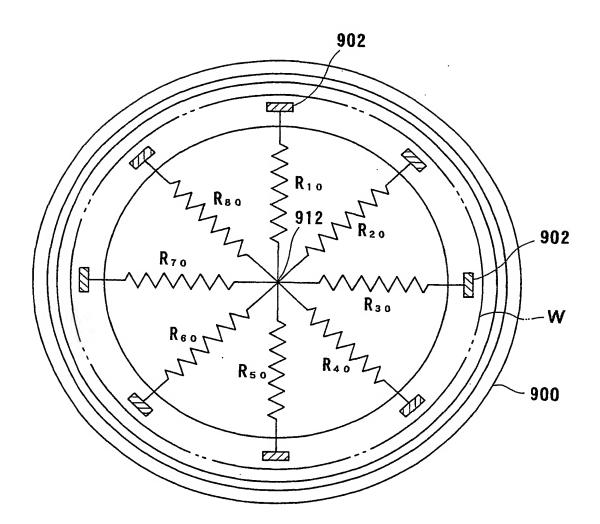




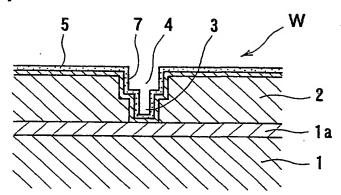
F/G.60



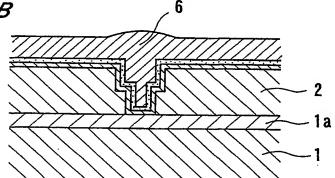
F | G. 6 1



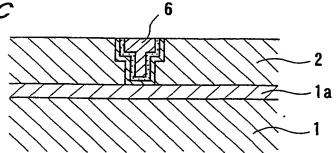
F I G. 62A



F I G. 62B



F | G. 62C

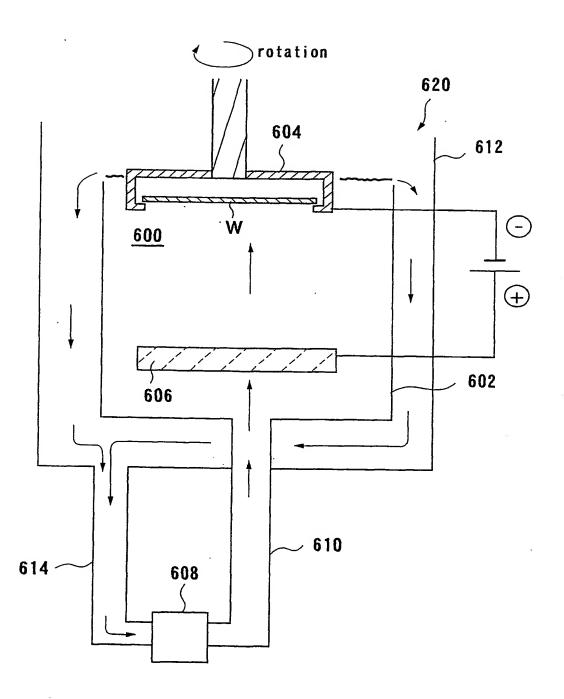


59/89

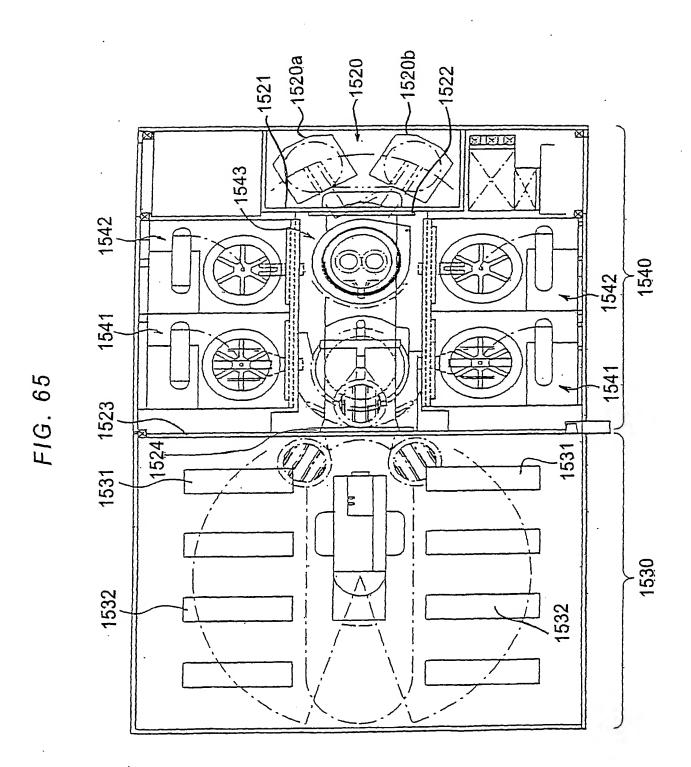
CMP device 20 copper plating device seed layer forming device 16 barrier layer forming device lithography and etching device isolation film forming device

F1G.63

F 1 G. 64



61/89



62/89

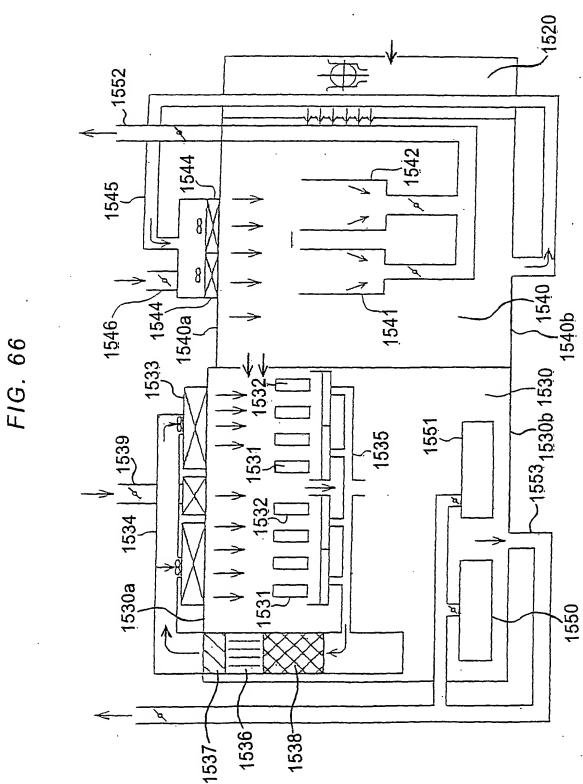


FIG. 67

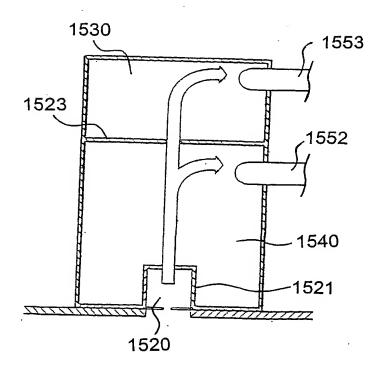


FIG. 68

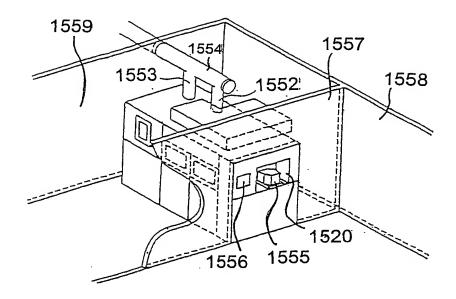
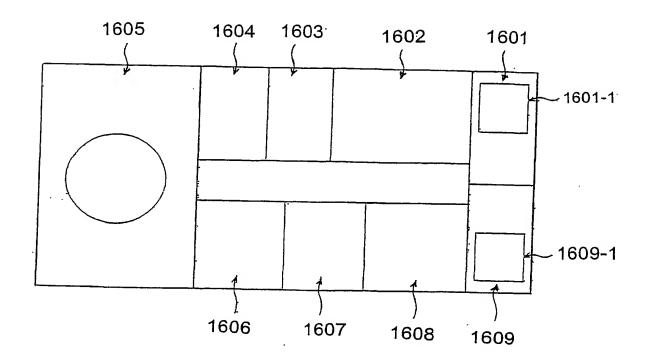


FIG. 69



66/89

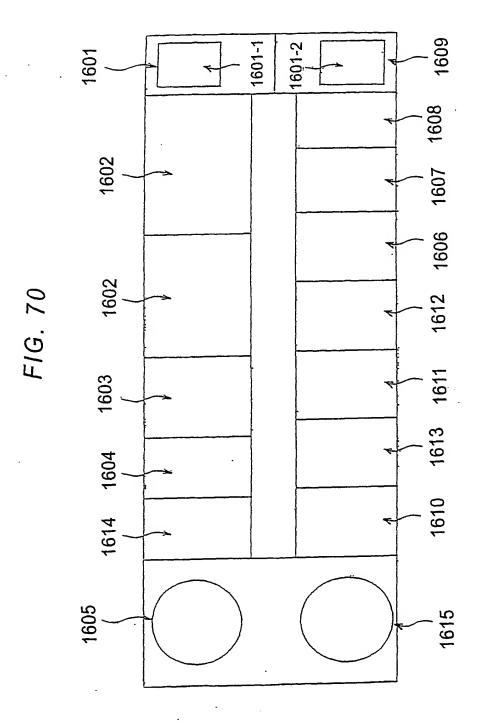


FIG. 71

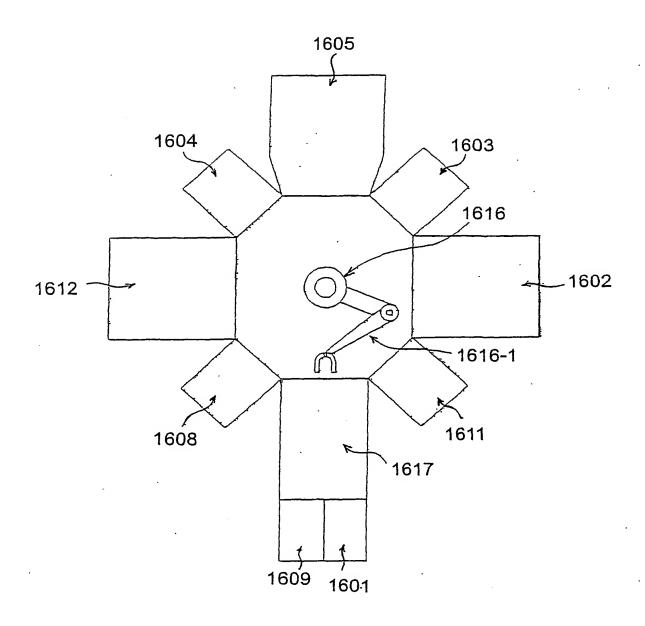


FIG. 72

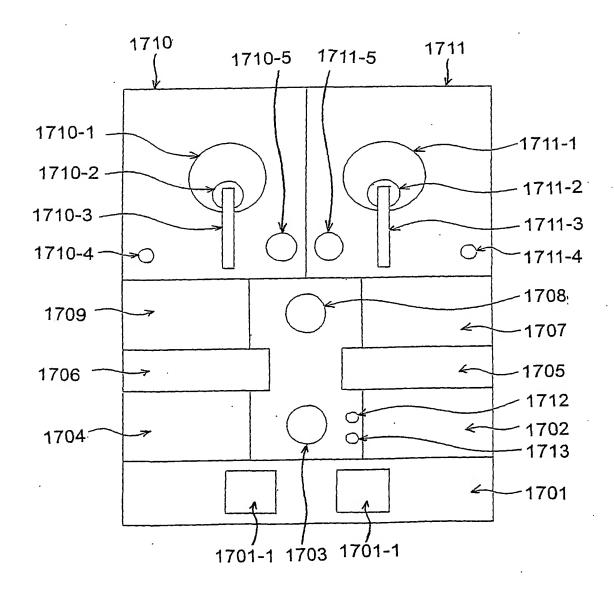
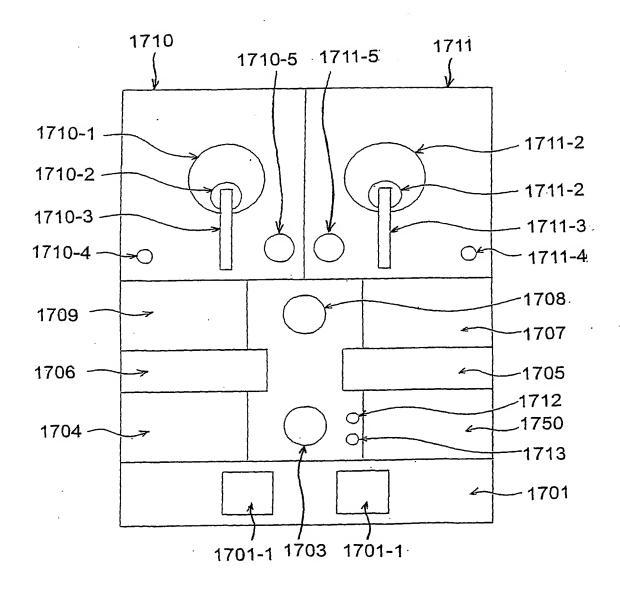


FIG. 73



PCT/JP01/10590

FIG. 74

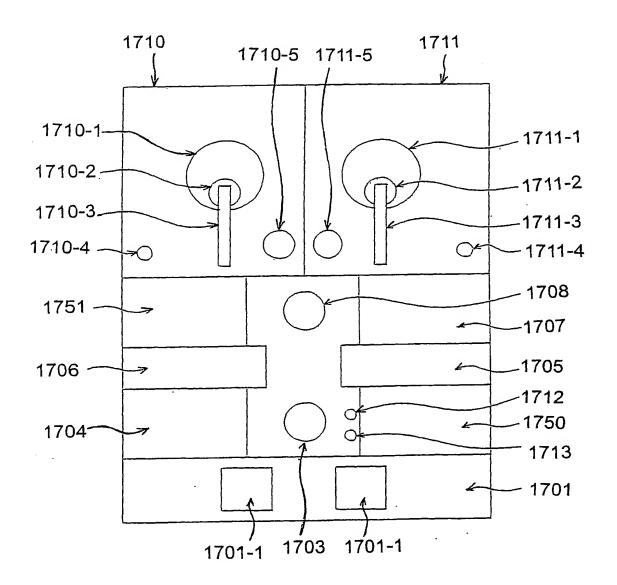


FIG. 75

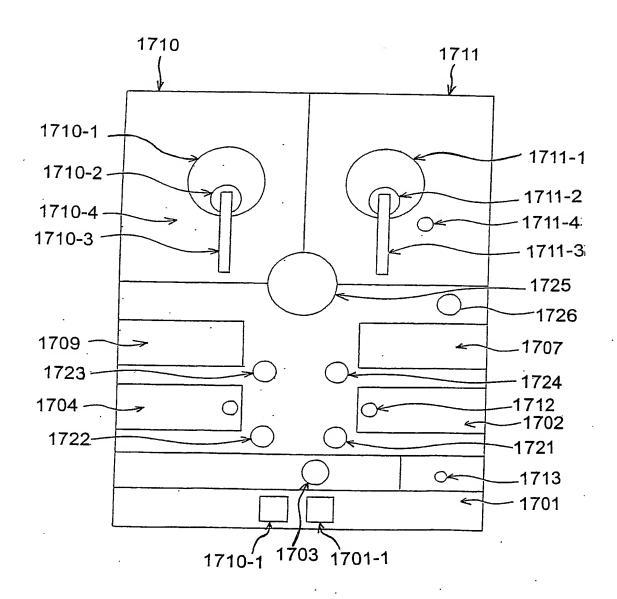
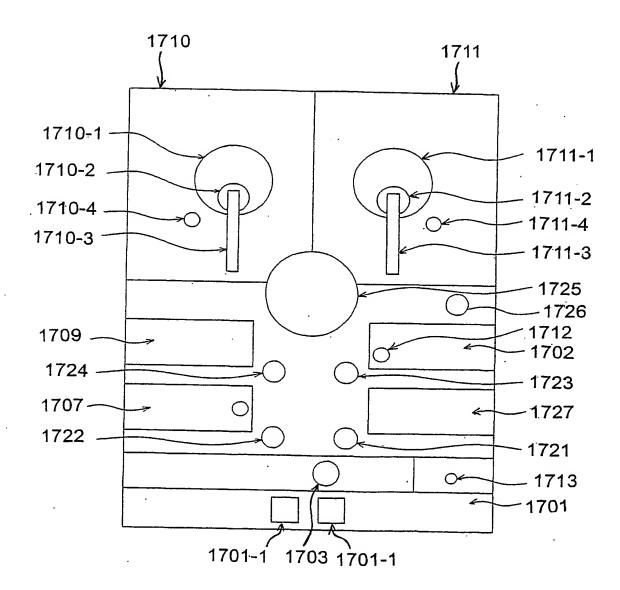
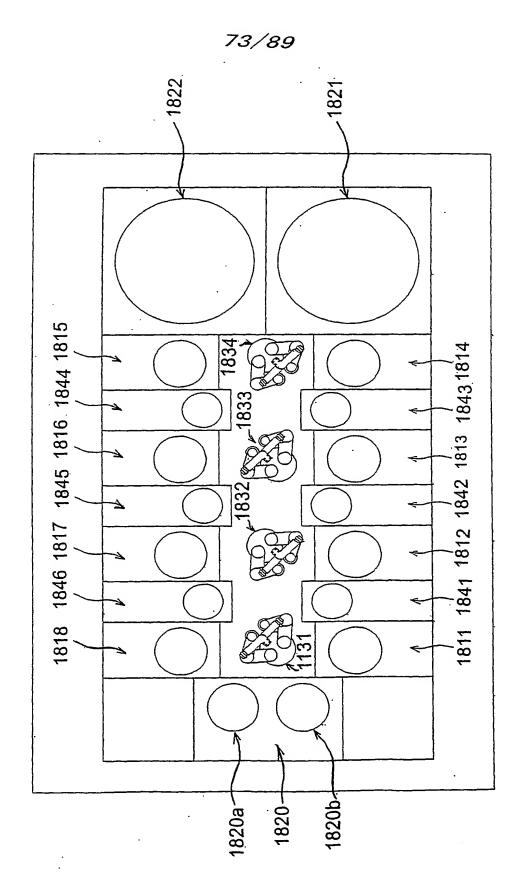


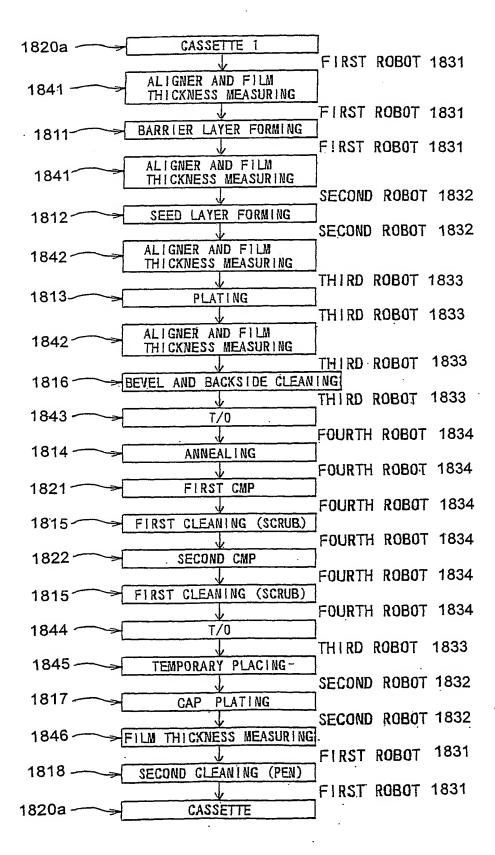
FIG. 76



F16. 7



74/89 FIG. 78



75/89

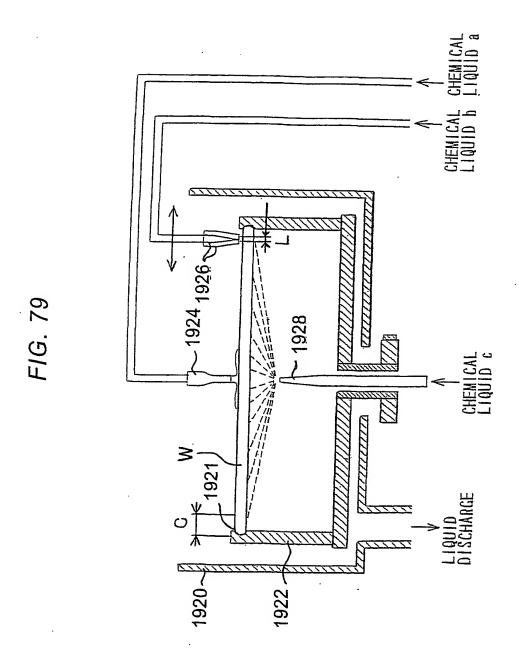


FIG. 80

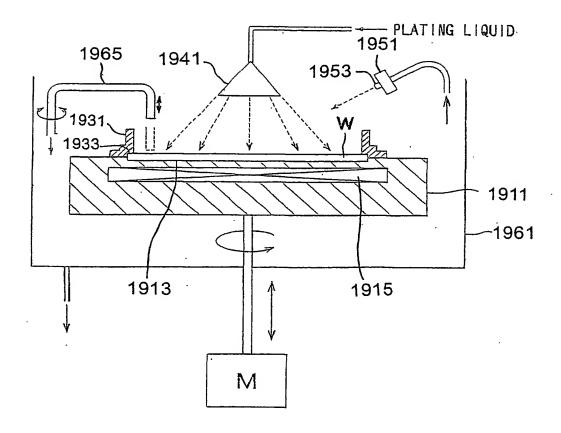
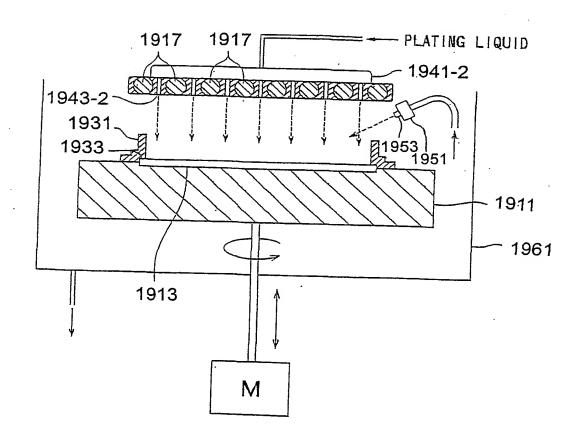
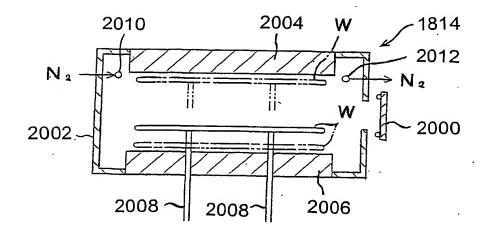


FIG. 81



78/89

FIG. 82



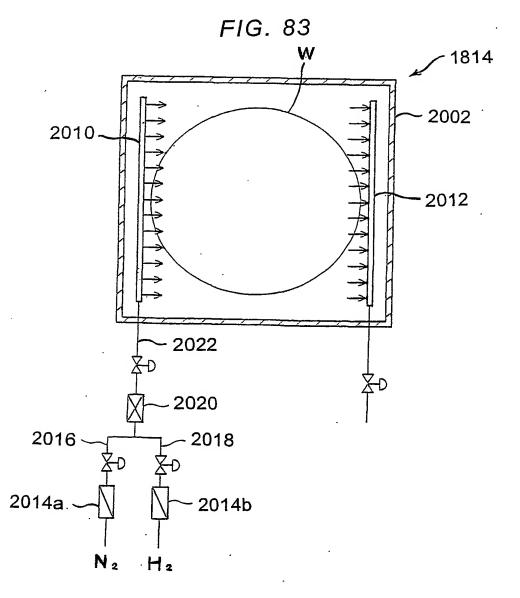


FIG. 84

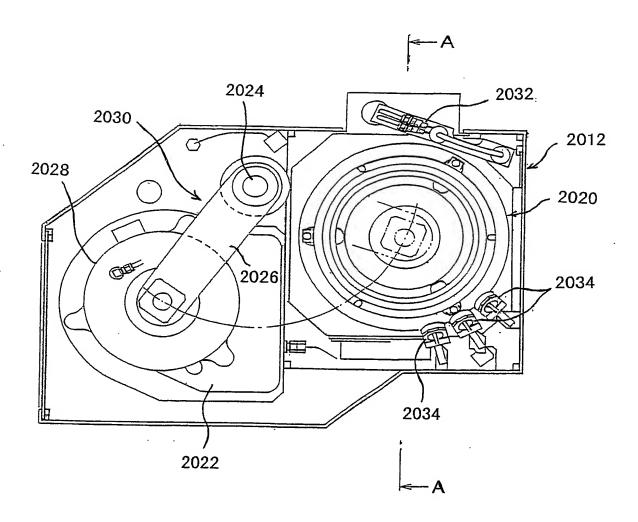


FIG. 85

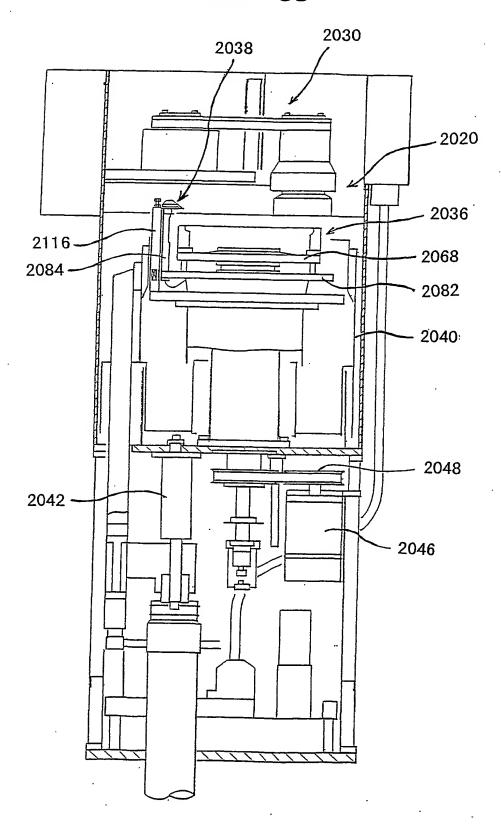
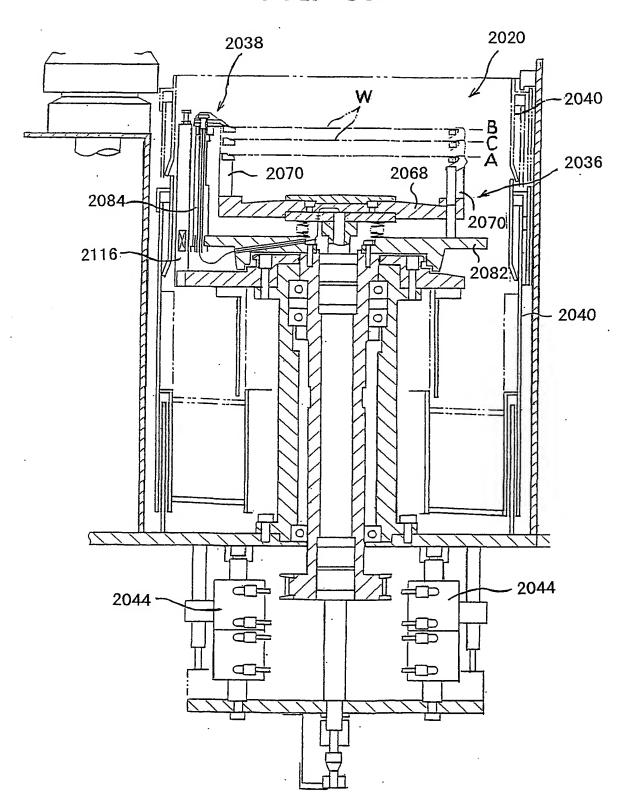


FIG. 86



82/89

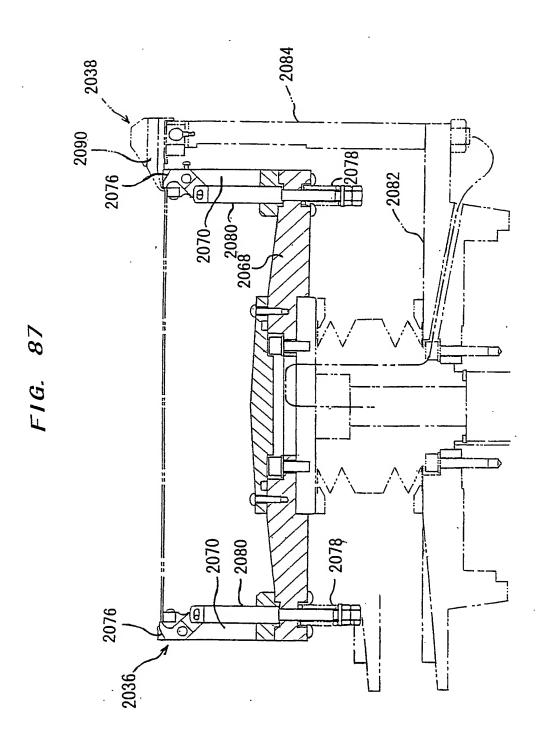
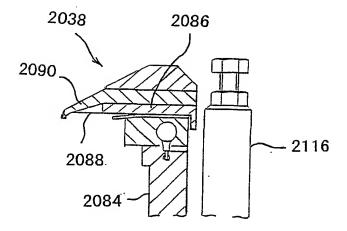
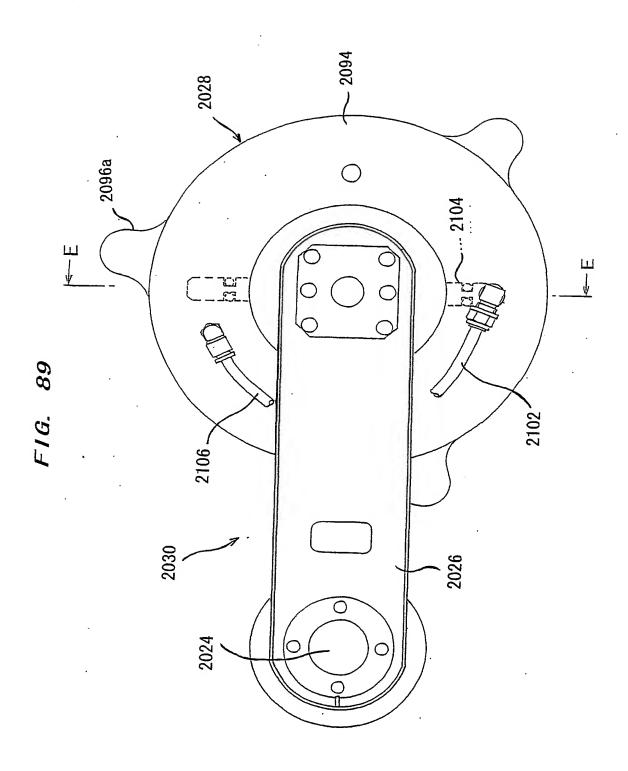


FIG. 88





85/89

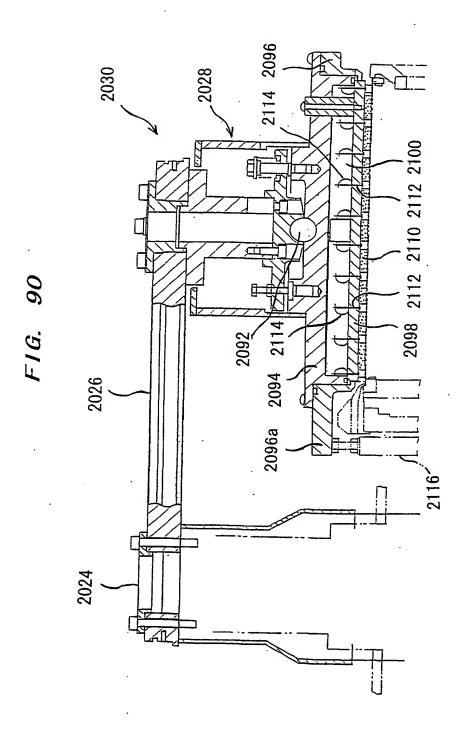


FIG. 91

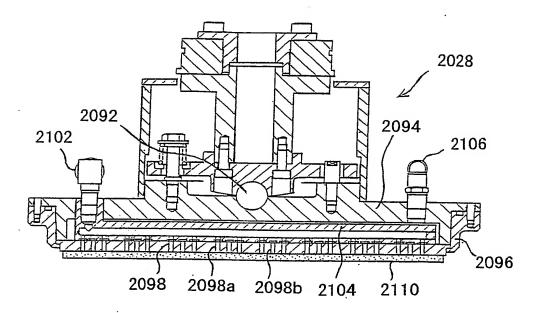


FIG. 92

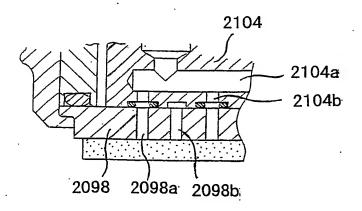


FIG. 93

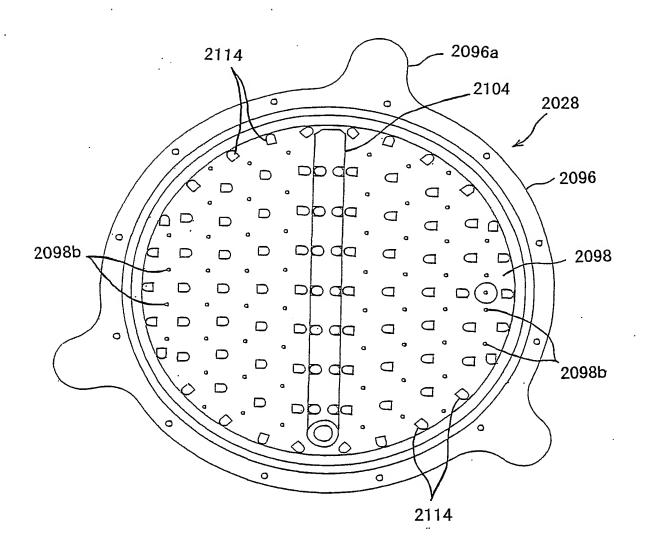


FIG. 94

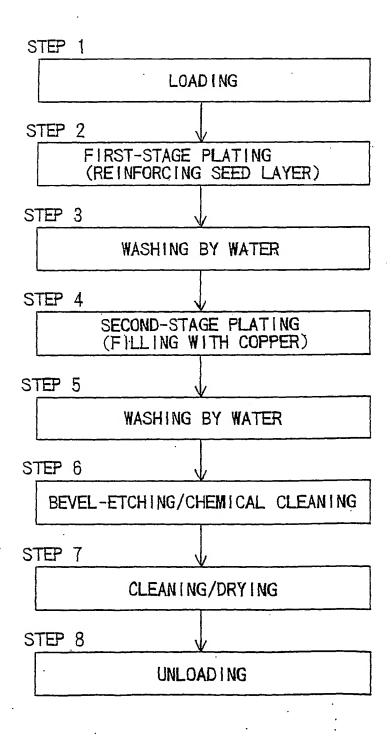


FIG. 95A

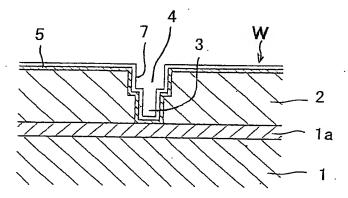


FIG. 95B

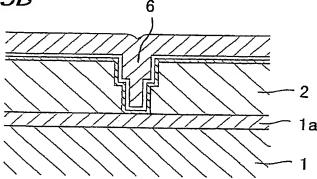


FIG. 95C

